

ABSTRACT

5           A method for fabricating an integrated circuit using a photo-lithographic  
process includes the steps of placing at least two anti-reflective coating layers  
between a reflective surface and another material. The indices of refraction,  
absorptions, and thicknesses of the at least two anti-reflective coating layers are  
chosen such that the amplitudes and phase differences of radiation reflected from the  
10 anti-reflective coating layers, as well as any other reflective surfaces below the anti-  
reflective coating layers, mutually cancel when combined. The invention may be  
practiced using more than two layers of anti-reflective coating. Multiple layers of  
anti-reflective coating may be used below an inter-level dielectric, in which case they  
may serve the additional purpose of functioning as an etch-stop.

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